

What is Claimed is:

1. A carrier module for a semiconductor device test handler comprising:

a carrier module body;

a device seating part in an underside part of the carrier module body;

at least one pair of first latches at opposite sides of the device seating part arranged opposite to, and movable away from, or close to, each other, for holding, or releasing opposite side parts of the semiconductor device seated on the device seating part;

at least one pair of second latches rotatably fitted on opposite sides of the first latch, for holding an underside part of the semiconductor device seated on the device seating part, and releasing the semiconductor device interlocked with a releasing action of the first latch;

a latch button fitted in an upper part of the carrier module to move in up/down directions and coupled to one end of the first latch, for moving up and down to make the first latch to move; and

a first elastic member, and a second elastic member for elastic supporting of the first latch, and the second latch.

2. The carrier module as claimed in claim 1, further comprising:

projections from opposite sides of a lower part of the second latch; and

latch pushers projected upward from opposite side parts of a test socket, to which the semiconductor device is brought into electric contact, and at which the semiconductor device is tested, opposite to the projections,

thereby, when the semiconductor device on the device seating part is brought into contact with the test socket, the projection of the second latch comes into contact with the latch pusher, to rotate the second latch outward, to release the holding on the semiconductor

device by the second latch.

3. The carrier module as claimed in claim 1, further comprising a plurality of tips extended from a fore end of the first latch between adjacent leads or balls on the semiconductor device, for supporting the underside edge of the semiconductor device.

4. The carrier module as claimed in claim 2, further comprising a plurality of supplementary tips extended from a fore end of the first latch between adjacent leads or balls on the semiconductor device, for supporting the underside edge of the semiconductor device.

5. The carrier module as claimed in claim 1, wherein the one end of the first latch is rotatably coupled to the latch button with a connection pin.

6. The carrier module as claimed in claim 5, further comprising:
a slanted guide slot of a long hole form in a central part in the first latch, and
a guide pin fixed to the carrier module body so as to be inserted in the guide slot for guiding movement of the first latch.

7. The carrier module as claimed in claim 1, further comprising a latch moving piece projected from the first latch so as to contact with an inside surface of the second latch, to rotate the second latch outward to release the semiconductor device when the first latch moves away and releases the semiconductor device.

8. The carrier module as claimed in claim 6, further comprising a latch moving piece

projected from the first latch so as to contact with an inside surface of the second latch, to rotate the second latch outward to release the semiconductor device when the first latch moves away and releases the semiconductor device.

9. The carrier module as claimed in claim 1, wherein two pairs of the first latches are arranged on opposite sides of the second latch.

10. The carrier module as claimed in claim 1, wherein the first latch, and the second latch are arranged in diagonal directions to each other, respectively.